

IRF330-333/IRF730-733

MTM/MTP5N35/5N40

N-Channel Power MOSFETs, 5.5 A, 350 V/400 V

Power And Discrete Division

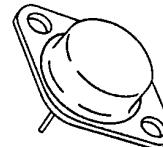
T-39-11

Description

These devices are n-channel, enhancement mode, power MOSFETs designed especially for high voltage, high speed applications, such as off-line switching power supplies, UPS, AC and DC motor controls, relay and solenoid drivers.

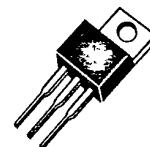
- V_{GS} Rated at ± 20 V
- Silicon Gate for Fast Switching Speeds
- $I_{DS(on)}$, $V_{DS(on)}$, SOA and $V_{GS(th)}$ Specified at Elevated Temperature
- Rugged

TO-204AA



IS00020F

TO-220AB



IS00010F

IRF330

IRF331

IRF332

IRF333

MTM5N35

MTM5N40

IRF730

IRF731

IRF732

IRF733

MTP5N35

MTP5N40

Maximum Ratings

Symbol	Characteristic	Rating IRF330/332 IRF730/732 MTM/MTP5N40	Rating IRF331/333 IRF731/733 MTM/MTP5N35	Unit
V_{DSS}	Drain to Source Voltage	400	350	V
V_{DGR}	Drain to Gate Voltage $R_{GS} = 1.0 \text{ M}\Omega$	400	350	V
V_{GS}	Gate to Source Voltage	± 20	± 20	V
T_J , T_{stg}	Operating Junction and Storage Temperature	-55 to +150	-55 to +150	°C
T_L	Maximum Lead Temperature for Soldering Purposes, 1/8" From Case for 5 s	275	275	°C

Maximum On-State Characteristics

		IRF330/331 IRF730/731	IRF332/333 IRF732/733	MTM5N35/40 MTP5N35/40	
$R_{DS(on)}$	Static Drain-to-Source On Resistance	1.0	1.5	1.0	Ω
I_D	Drain Current Continuous Pulsed	5.5 22	4.5 22	5.0 22	A

Maximum Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.67	1.67	1.67	°C/W
P_D	Total Power Dissipation at $T_C = 25^\circ\text{C}$	75	75	75	W

Notes

For information concerning connection diagram and package outline, refer to Section 7.

Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Characteristic	Min	Max	Unit	Test Conditions	
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain Source Breakdown Voltage ¹			V	$V_{\text{GS}} = 0 \text{ V}, I_D = 250 \mu\text{A}$	
	IRF330/332/730/732	400				
	IRF331/333/731/733	350				
I_{DSS}	Zero Gate Voltage Drain Current		250	μA	$V_{\text{DS}} = \text{Rated } V_{\text{DSS}}, V_{\text{GS}} = 0 \text{ V}$	
			1000	μA	$V_{\text{DS}} = 0.8 \times \text{Rated } V_{\text{DSS}}, V_{\text{GS}} = 0 \text{ V}, T_C = 125^\circ\text{C}$	
I_{GSS}	Gate-Body Leakage Current IRF330-333 IRF730-733		± 100 ± 500	nA	$V_{\text{GS}} = \pm 20 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	
On Characteristics						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	2.0	4.0	V	$I_D = 250 \mu\text{A}, V_{\text{DS}} = V_{\text{GS}}$	
$R_{\text{DS(on)}}$	Static Drain-Source On-Resistance ²			Ω	$V_{\text{GS}} = 10 \text{ V}, I_D = 3.0 \text{ A}$	
			1.0			
			1.5			
g_{fs}	Forward Transconductance	3.0		S (Ω)	$V_{\text{DS}} = 10 \text{ V}, I_D = 3.0 \text{ A}$	
Dynamic Characteristics						
C_{iss}	Input Capacitance		900	pF	$V_{\text{DS}} = 25 \text{ V}, V_{\text{GS}} = 0 \text{ V}$ $f = 1.0 \text{ MHz}$	
C_{oss}	Output Capacitance		300	pF		
C_{rss}	Reverse Transfer Capacitance		80	pF		
Switching Characteristics ($T_C = 25^\circ\text{C}$, Figures 12, 13)						
$t_{\text{d(on)}}$	Turn-On Delay Time		30	ns	$V_{\text{DD}} = 175 \text{ V}, I_D = 3.0 \text{ A}$ $V_{\text{GS}} = 10 \text{ V}, R_{\text{GEN}} = 15 \Omega$ $R_{\text{GS}} = 15 \Omega$	
t_r	Rise Time		35	ns		
$t_{\text{d(off)}}$	Turn-Off Delay Time		55	ns		
t_f	Fall Time		35	ns		
Q_g	Total Gate Charge		30	nC		
Symbol Characteristic Typ Max Unit Test Conditions						
Source-Drain Diode Characteristics						
V_{SD}	Diode Forward Voltage IRF330/331/730/731 IRF332/333/732/733		1.6	V	$I_S = 5.5 \text{ A}; V_{\text{GS}} = 0 \text{ V}$	
			1.5	V	$I_S = 4.5 \text{ A}; V_{\text{GS}} = 0 \text{ V}$	
t_{rr}	Reverse Recovery Time	400		ns	$I_S = 5.5 \text{ A}; dI_S/dt = 100 \text{ A}/\mu\text{s}$	

Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Characteristic	Min	Max	Unit	Test Conditions
Off Characteristics					
$V_{(\text{BR})\text{DSS}}$	Drain Source Breakdown Voltage ¹ MTM/MTP5N40 MTM/MTP5N35			V	$V_{GS} = 0 \text{ V}, I_D = 5.0 \text{ mA}$
		400			
		350			
$I_{\text{DS}}^{\text{SS}}$	Zero Gate Voltage Drain Current		0.25	mA	$V_{DS} = 0.85 \times \text{Rated } V_{DSS}, V_{GS} = 0 \text{ V}$
			2.5	mA	$V_{DS} = 0.85 \times \text{Rated } V_{DSS}, V_{GS} = 0 \text{ V}, T_C = 100^\circ\text{C}$
$I_{GS\text{S}}$	Gate-Body Leakage Current		± 500	nA	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$
On Characteristics					
$V_{GS(\text{th})}$	Gate Threshold Voltage	2.0	4.5	V	$I_D = 1.0 \text{ mA}, V_{DS} = V_{GS}$
		1.5	4.0	V	$I_D = 1.0 \text{ mA}, V_{DS} = V_{GS}, T_C = 100^\circ\text{C}$
$R_{DS(\text{on})}$	Static Drain-Source On-Resistance ²		1.0	Ω	$V_{GS} = 10 \text{ V}, I_D = 2.5 \text{ A}$
$V_{DS(\text{on})}$	Drain-Source On-Voltage ²		2.5	V	$V_{GS} = 10 \text{ V}, I_D = 2.5 \text{ A}$
			6.2	V	$V_{GS} = 10 \text{ V}, I_D = 5.0 \text{ A}$
			5.0	V	$V_{GS} = 10 \text{ V}, I_D = 2.5 \text{ A}, T_C = 100^\circ\text{C}$
g_{fs}	Forward Transconductance	2.0		S (μ)	$V_{DS} = 10 \text{ V}, I_D = 2.5 \text{ A}$
Dynamic Characteristics					
C_{iss}	Input Capacitance		1200	pF	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}$ $f = 1.0 \text{ MHz}$
C_{oss}	Output Capacitance		300	pF	
C_{rss}	Reverse Transfer Capacitance		80	pF	
Switching Characteristics ($T_C = 25^\circ\text{C}$, Figures 12, 13)³					
$t_{d(on)}$	Turn-On Delay Time		50	ns	$V_{DD} = 25 \text{ V}, I_D = 2.5 \text{ A}$ $V_{GS} = 10 \text{ V}, R_{\text{GEN}} = 50 \Omega$ $R_{GS} = 50 \Omega$
t_r	Rise Time		100	ns	
$t_{d(off)}$	Turn-Off Delay Time		200	ns	
t_f	Fall Time		100	ns	
Q_g	Total Gate Charge		30	nC	$V_{GS} = 10 \text{ V}, I_D = 7.0 \text{ A}$ $V_{DD} = 180 \text{ V}$

Notes

- $T_J = +25^\circ\text{C}$ to $+150^\circ\text{C}$
- Pulse test: Pulse width $\leq 80 \mu\text{s}$, Duty cycle $\leq 1\%$
- Switching time measurements performed on LEM TR-58 test equipment.

Typical Performance Curves

Figure 1 Output Characteristics

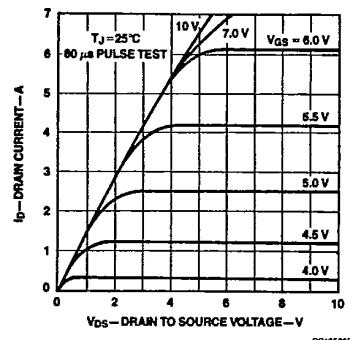


Figure 3 Transfer Characteristics

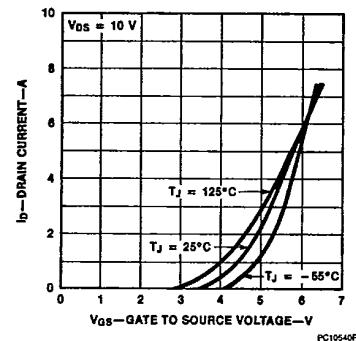
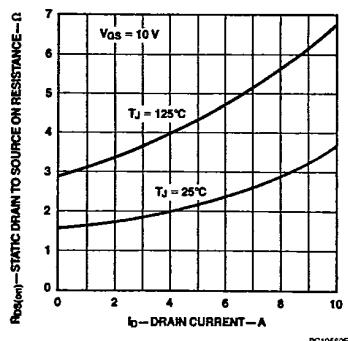


Figure 5 Static Drain to Source On-Resistance vs Drain Current



Figures 4-6 for IRF332/333/732/733 only.

Figure 2 Static Drain to Source Resistance vs Drain Current

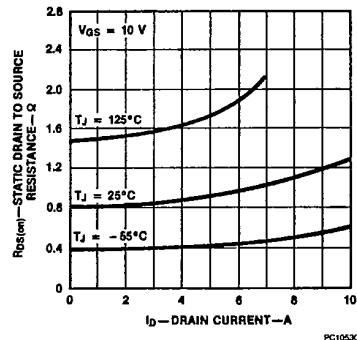


Figure 4 Output Characteristics

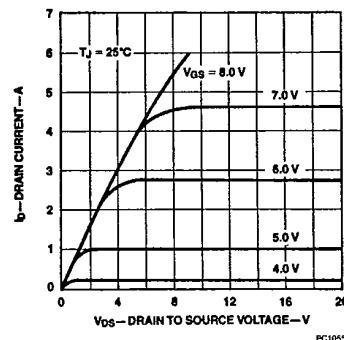
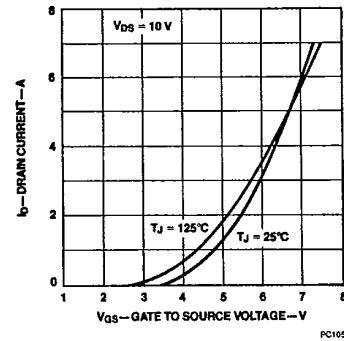


Figure 6 Transfer Characteristics



Typical Performance Curves (Cont.)

Figure 7 Temperature Variation of Gate to Source Threshold Voltage

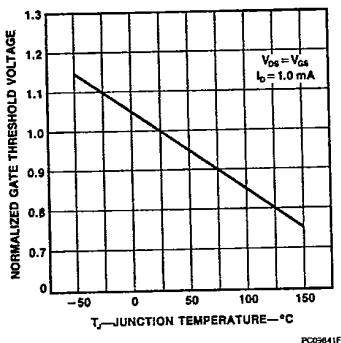


Figure 9 Gate to Source Voltage vs Total Gate Charge

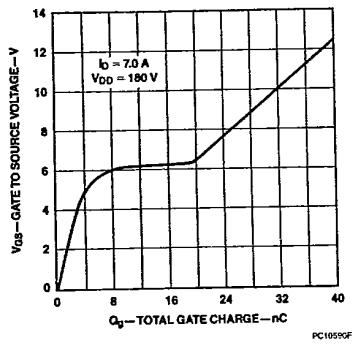


Figure 11 Transient Thermal Resistance

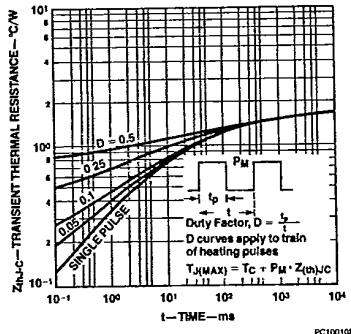


Figure 8 Capacitance vs Drain to Source Voltage

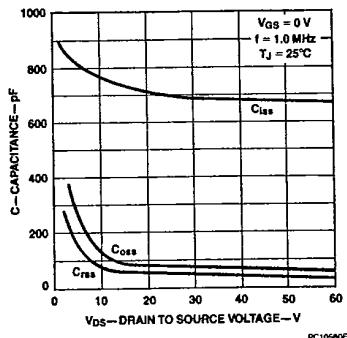
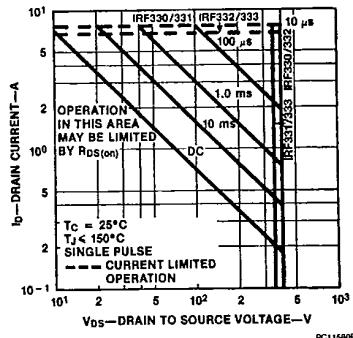
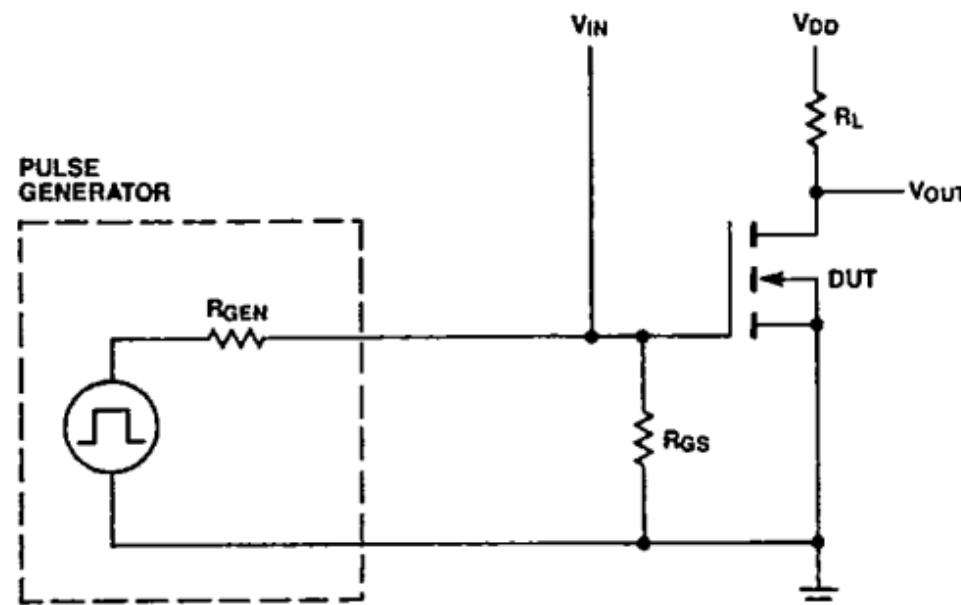


Figure 10 Forward Biased Safe Operating Area



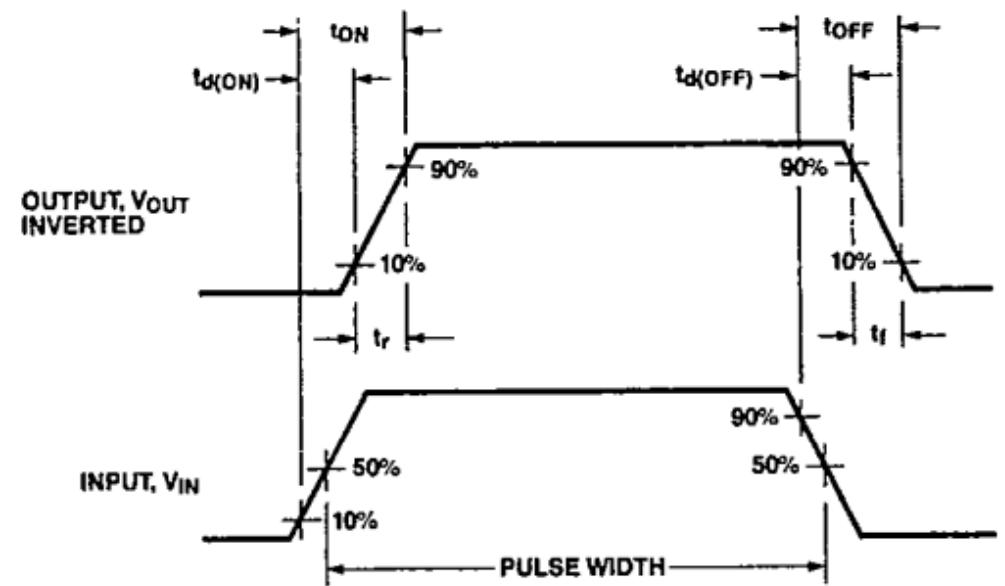
Typical Electrical Characteristics

Figure 12 Switching Test Circuit



CR04450F

Figure 13 Switching Waveforms



WF00600F